

The listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) A method of ~~supporting a flexible substrate manufacturing a semiconductor device~~, comprising the ~~[[step]]~~ steps of:

fixing ~~[[the]]~~ a flexible substrate having thermal shrinkage to a holding frame having ~~a smaller thermal expansion coefficient than 10 ppm/°C;~~

heating the fixed flexible substrate at a temperature that the flexible substrate is thermal-shrunk, and

forming a conductive film on the flexible substrate by a sputtering method.

2. (Currently Amended) A method of ~~supporting a flexible substrate manufacturing a semiconductor device~~, comprising the ~~[[step]]~~ steps of:

fixing an outer circumference of ~~[[the]]~~ a flexible substrate having thermal shrinkage to a frame-shaped holding frame having ~~a smaller thermal expansion coefficient than 10 ppm/°C;~~

heating the fixed flexible substrate at a temperature that the flexible substrate is thermal-shrunk, and

forming an amorphous semiconductor film on the flexible substrate by a plasma CVD method.

3. (Currently Amended) A method of ~~supporting a flexible substrate manufacturing a semiconductor device~~ according to claim 1, wherein the flexible substrate comprises one selected from polyethylene naphthalate, polyethylene terephthalate, polyether sulfone, and polyimide.

4. (Currently Amended) A method of ~~supporting a flexible substrate~~ manufacturing a semiconductor device according to claim 1, wherein the holding frame comprises a ceramics-metal complex.

5. (Currently Amended) A method of ~~supporting a flexible substrate~~ manufacturing a semiconductor device according to claim 2, wherein the flexible substrate comprises one selected from polyethylene naphthalate, polyethylene terephthalate, polyether sulfone, and polyimide.

6. (Currently Amended) A method of ~~supporting a flexible substrate~~ manufacturing a semiconductor device according to claim 2, wherein the holding frame comprises a ceramics-metal complex.

7. (Currently Amended) A method of manufacturing a semiconductor device, comprising the ~~[[step]]~~ steps of:

fixing a flexible substrate having thermal shrinkage to a holding frame ~~having a smaller thermal expansion coefficient than 10 ppm/°C; [[and]]~~

heating the flexible substrate at a temperature that the flexible substrate is ~~thermal-shrunk by 0.2% or more; and~~

forming a predetermined pattern over the flexible substrate by screen printing.

8. (Currently Amended) A method of manufacturing a semiconductor device, comprising the ~~[[step]]~~ steps of:

fixing an outer circumference of a flexible substrate having thermal shrinkage to a frame-shaped holding frame ~~having a smaller thermal expansion coefficient than 10 ppm/°C; [[and]]~~

heating the flexible substrate at a temperature that the flexible substrate is ~~thermal-shrunk by 0.2% or more, and~~

forming a predetermined pattern over the flexible substrate by laser processing.

9. (Currently Amended) A method of manufacturing a semiconductor device, comprising the [[step]] steps of:

fixing an outer circumference of a flexible substrate having thermal shrinkage to a frame-shaped holding frame having a smaller thermal expansion coefficient than 10 ppm/°C;

heating the fixed flexible substrate at a temperature that the flexible substrate is thermal-shrunk by 0.2% or more; and

forming a conductive film on the flexible substrate by a sputtering method.

10. (Currently Amended) A method of manufacturing a semiconductor device, comprising the [[step]] steps of:

fixing an outer circumference of a flexible substrate having thermal shrinkage to a frame-shaped holding frame having a smaller thermal expansion coefficient than 10 ppm/°C;

heating the fixed flexible substrate at a temperature that the flexible substrate is thermal-shrunk by 0.2% or more; and

forming an amorphous semiconductor film on the flexible substrate by a plasma CVD method.

11. (Original) A method of manufacturing a semiconductor device, comprising:

a first step of fixing an outer circumference of a flexible substrate having thermal shrinkage to a frame-shaped holding frame having a smaller thermal expansion coefficient than 10 ppm/°C and then heating the flexible substrate at a temperature that the flexible substrate is thermal-shrunk by 0.2% or more; and

a second step of forming a predetermined pattern over the flexible substrate by screen printing.

12. (Original) A method of manufacturing a semiconductor device, comprising:  
a first step of fixing an outer circumference of a flexible substrate having thermal shrinkage to a frame-shaped holding frame having a smaller thermal expansion coefficient than 10 ppm/°C and then heating the flexible substrate at a temperature that the flexible substrate is thermal-shrunk by 0.2% or more; and  
a second step of forming a predetermined pattern over the flexible substrate by laser processing.

13. (Previously Presented) A method of manufacturing a semiconductor device according to claim 11, wherein a position of the flexible substrate is aligned by an alignment means of the holding frame in the second step.

14. (Previously Presented) A method of manufacturing a semiconductor device according to claim 12, wherein a position of the flexible substrate is aligned by an alignment means of the holding frame in the second step.

15. (Previously Presented) A method of manufacturing a semiconductor device according to claim 7, wherein the flexible substrate comprises one selected from polyethylene naphthalate, polyethylene terephthalate, polyether sulfone, and polyimide.

16. (Previously Presented) A method of manufacturing a semiconductor device according to claim 7, wherein the holding frame comprises a ceramics-metal complex.

17. (Previously Presented) A method of manufacturing a semiconductor device according to claim 8, wherein the flexible substrate comprises one selected from polyethylene naphthalate, polyethylene terephthalate, polyether sulfone, and polyimide.

18. (Currently Amended) A method of ~~supporting a flexible substrate~~ manufacturing a semiconductor device according to claim 8, wherein the holding frame comprises a ceramics-metal complex.

19. (Previously Presented) A method of manufacturing a semiconductor device according to claim 9, wherein the flexible substrate comprises one selected from polyethylene naphthalate, polyethylene terephthalate, polyether sulfone, and polyimide.

20. (Currently Amended) A method of ~~supporting a flexible substrate~~ manufacturing a semiconductor device according to claim 9, wherein the holding frame comprises a ceramics-metal complex.

21. (Previously Presented) A method of manufacturing a semiconductor device according to claim 10, wherein the flexible substrate comprises one selected from polyethylene naphthalate, polyethylene terephthalate, polyether sulfone, and polyimide.

22. (Currently Amended) A method of ~~supporting a flexible substrate~~ manufacturing a semiconductor device according to claim 10, wherein the holding frame comprises a ceramics-metal complex.

23. (Previously Presented) A method of manufacturing a semiconductor device according to claim 11, wherein the flexible substrate comprises one selected from polyethylene naphthalate, polyethylene terephthalate, polyether sulfone, and polyimide.

24. (Currently Amended) A method of ~~supporting a flexible substrate~~ manufacturing a semiconductor device according to claim 11, wherein the holding frame comprises a ceramics-metal complex.

25. (Previously Presented) A method of manufacturing a semiconductor device according to claim 12, wherein the flexible substrate comprises one selected from polyethylene naphthalate, polyethylene terephthalate, polyether sulfone, and polyimide.

26. (Currently Amended) A method of ~~supporting a flexible substrate~~ manufacturing a semiconductor device according to claim 12, wherein the holding frame comprises a ceramics-metal complex.

27.-30. (Canceled)

31. (Currently Amended) A method of ~~supporting a flexible substrate~~ manufacturing a semiconductor device according to claim 9, wherein the thermal expansion coefficient is 6.5 ppm/°C or smaller.

32. (Currently Amended) A method of ~~supporting a flexible substrate~~ manufacturing a semiconductor device according to claim 10, wherein the thermal expansion coefficient is 6.5 ppm/°C or smaller.

33. (Currently Amended) A method of ~~supporting a flexible substrate~~ manufacturing a semiconductor device according to claim 11, wherein the thermal expansion coefficient is 6.5 ppm/°C or smaller.

34. (Currently Amended) A method of ~~supporting a flexible substrate~~ manufacturing a semiconductor device according to claim 12, wherein the thermal expansion coefficient is 6.5 ppm/°C or smaller.